

<b>PATENT ASSIGNMENT COVER SHEET</b>
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Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT4228130

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
DEEPUKUMAR M NAIR	01/11/2017
MICHAEL ARNETT SMITH	01/13/2017
JAMES M PARISI	01/12/2017
ELIZABETH D HUGHES	01/12/2017
WILLIAM E MCKINZIE III	01/11/2017
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	E. I. DU PONT DE NEMOURS AND COMPANY
<b>Street Address:</b>	974 CENTRE ROAD
<b>Internal Address:</b>	DUPONT LEGAL, CRP 721
<b>City:</b>	WILMINGTON
<b>State/Country:</b>	DELAWARE
<b>Postal Code:</b>	19810
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	14295647
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(302)355-0556
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	302-999-6887
<b>Email:</b>	dana.burkhart@dupont.com
<b>Correspondent Name:</b>	DANA BURKHART
<b>Address Line 1:</b>	974 CENTRE ROAD
<b>Address Line 2:</b>	CRP 721/2251
<b>Address Line 4:</b>	WILMINGTON, DELAWARE 19810
<b>ATTORNEY DOCKET NUMBER:</b>	EL1181-US-NP
<b>NAME OF SUBMITTER:</b>	DANA BURKHART
<b>SIGNATURE:</b>	/Dana Burkhart/
<b>DATE SIGNED:</b>	01/17/2017

**Total Attachments: 5**

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**NON-PROVISIONAL APPLICATION ASSIGNMENT**

We, the undersigned

DEEPUKUMAR M NAIR, MICHAEL ARNETT SMITH, JAMES M PARISI, ELIZABETH D HUGHES

Hereby declare that

We are the inventors of an invention entitled


METHOD OF FABRICATING ELECTROMAGNETIC BANDGAP (EBG) STRUCTURES FOR MICROWAVE/MILLIMETERWAVE APPLICATIONS USING LASER PROCESSING OF UNFIRED LOW TEMPERATURE CO-FIRED CERAMIC (LTCC) TAPE

which is disclosed in the United States Patent Application No. 14/295647 filed on June 04, 2014 and which is identified as Case Number EL1181-US-NP.

For valuable consideration, the receipt and adequacy of which is hereby acknowledged and in fulfillment of our pre-existing obligation of assignment, we hereby:

I. Sell, assign, and transfer unto E I DU PONT DE NEMOURS AND COMPANY, a corporation organized and existing under the laws of the State of Delaware in the United States of America and having its principal place of business at Wilmington, Delaware, hereinafter referred to as the assignee, (A) the entire right, title, and interest in and to: (1) the aforesaid application for Letters Patent, (2) any priority rights derived from the aforesaid application for Letters Patent by virtue of the International Convention for the Protection of Industrial Property and any other treaty or understanding for intellectual property for any and all member countries of the aforesaid International Convention or other treaty or understanding, (3) any and all inventions, whether joint or sole, disclosed in the aforesaid application for Letters Patent, (4) any and all applications for Letters Patent for any such inventions in any country whatsoever, (5) any and all patents for any such inventions in any country whatsoever; and (B) the sole right to (1) file such applications in its name or ours, (2) file such applications under the aforesaid International Convention or other treaty or understanding, (3) have said patents granted in its name or ours, and (4) enforce said patents and to sue for and recover profits and damages for any and all infringements thereof whether past or future; and

II. Agree, whenever requested, to communicate to said assignee, its successors, assigns, and legal representatives, any facts known to us respecting said inventions or the rights described above, to testify in any legal proceeding respecting said inventions or the rights described above, the location of that testimony to be in the country in which we reside or in the nearest country in which such testimony is legal should our country of residence prohibit such testimony, to execute all applications, papers or instruments necessary or required by said assignee, its successors, assigns and legal representatives, to carry into effect any of the provisions of this instrument, and generally to do everything possible to aid said assignee, its successors, assigns, and legal representatives to obtain and enforce proper patent protection for said inventions.



DEEPUKUMAR M NAIR (L.S.)  
DATE: 01/11/2017

ELIZABETH D HUGHES (L.S.)  
DATE:

MICHAEL ARNETT SMITH (L.S.)  
DATE:

JAMES M PARISI (L.S.)  
DATE:

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.....(L.S.)  
DEEPUKUMAR M NAIR  
DATE: \_\_\_\_\_

.....(L.S.)  
ELIZABETH D HUGHES  
DATE: \_\_\_\_\_

  
.....(L.S.)  
MICHAEL ARNETT SMITH  
DATE: 1/13/17

.....(L.S.)  
JAMES M PARISI  
DATE: \_\_\_\_\_

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organized and existing under the laws of the State of Delaware in the United States of America and having its  
principal place of business at Wilmington, Delaware, hereinafter referred to as the assignee, (A) the entire right,  
title, and interest in and to: (1) the aforesaid application for Letters Patent, (2) any priority rights derived from the  
aforesaid application for Letters Patent by virtue of the International Convention for the Protection of Industrial  
Property and any other treaty or understanding for intellectual property for any and all member countries of the  
aforesaid International Convention or other treaty or understanding, (3) any and all inventions, whether joint or  
sole, disclosed in the aforesaid application for Letters Patent, (4) any and all applications for Letters Patent for  
any such inventions in any country whatsoever, (5) any and all patents for any such inventions in any country  
whatsoever; and (B) the sole right to (1) file such applications in its name or ours, (2) file such applications  
under the aforesaid International Convention or other treaty or understanding, (3) have said patents granted in  
its name or ours, and (4) enforce said patents and to sue for and recover profits and damages for any and all  
infringements thereof whether past or future; and

II. Agree, whenever requested, to communicate to said assignee, its successors, assigns, and legal  
representatives, any facts known to us respecting said inventions or the rights described above, to testify in any  
legal proceeding respecting said inventions or the rights described above, the location of that testimony to be in  
the country in which we reside or in the nearest country in which such testimony is legal should our country of  
residence prohibit such testimony, to execute all applications, papers or instruments necessary or required by  
said assignee, its successors, assigns and legal representatives, to carry into effect any of the provisions of this  
instrument, and generally to do everything possible to aid said assignee, its successors, assigns, and legal  
representatives to obtain and enforce proper patent protection for said inventions.

\_\_\_\_\_(L.S.)  
DEEPUKUMAR M NAIR  
DATE: \_\_\_\_\_

\_\_\_\_\_(L.S.)  
ELIZABETH D HUGHES  
DATE: \_\_\_\_\_

\_\_\_\_\_(L.S.)  
MICHAEL ARNETT SMITH  
DATE: \_\_\_\_\_

\_\_\_\_\_(L.S.)  
JAMES M PARISI  
DATE: 1-12-17

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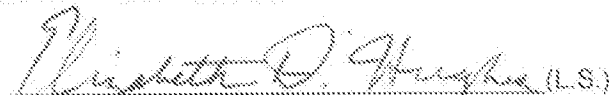
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I. Sell, assign, and transfer unto E I DU PONT DE NEMOURS AND COMPANY, a corporation organized and existing under the laws of the State of Delaware in the United States of America and having its principal place of business at Wilmington, Delaware, hereinafter referred to as the assignee, (A) the entire right, title, and interest in and to: (1) the aforesaid application for Letters Patent, (2) any priority rights derived from the aforesaid application for Letters Patent by virtue of the International Convention for the Protection of Industrial Property and any other treaty or understanding for intellectual property for any and all member countries of the aforesaid International Convention or other treaty or understanding, (3) any and all inventions, whether joint or sole, disclosed in the aforesaid application for Letters Patent, (4) any and all applications for Letters Patent for any such inventions in any country whatsoever, (5) any and all patents for any such inventions in any country whatsoever, and (B) the sole right to (1) file such applications in its name or ours, (2) file such applications under the aforesaid International Convention or other treaty or understanding, (3) have said patents granted in its name or ours, and (4) enforce said patents and to sue for and recover profits and damages for any and all infringements thereof whether past or future; and

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.....(L.S.)  
DEEPUKUMAR M NAIR  
DATE: .....

  
.....(L.S.)  
ELIZABETH D HUGHES  
DATE: 1/12/2017

.....(L.S.)  
MICHAEL ARNETT SMITH  
DATE: .....

.....(L.S.)  
JAMES M PARISI  
DATE: .....

# NON-PROVISIONAL APPLICATION ASSIGNMENT

We, the undersigned

WILLIAM E. MCKINZIE, III

Hereby declare that

We are the inventors of an invention entitled

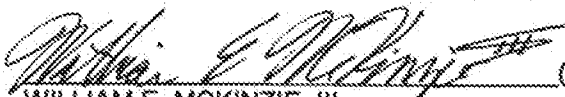
METHOD OF FABRICATING ELECTROMAGNETIC BANDGAP (EBG) STRUCTURES FOR  
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For valuable consideration, the receipt and adequacy of which is hereby acknowledged and in fulfillment of our pre-existing obligation of assignment, we hereby:

I. Sell, assign, and transfer unto WEMTEC INC, a corporation organized and existing under the laws of the State of Delaware in the United States of America and having its principal place of business at Fulton, Maryland, hereinafter referred to as the assignee, (A) the entire right, title, and interest in and to: (1) the aforesaid application for Letters Patent, (2) any priority rights derived from the aforesaid application for Letters Patent by virtue of the International Convention for the Protection of Industrial Property and any other treaty or understanding for intellectual property for any and all member countries of the aforesaid International Convention or other treaty or understanding, (3) any and all inventions, whether joint or sole, disclosed in the aforesaid application for Letters Patent, (4) any and all applications for Letters Patent for any such inventions in any country whatsoever, (5) any and all patents for any such inventions in any country whatsoever; and (B) the sole right to (1) file such applications in its name or ours, (2) file such applications under the aforesaid International Convention or other treaty or understanding, (3) have said patents granted in its name or ours, and (4) enforce said patents and to sue for and recover profits and damages for any and all infringements thereof whether past or future; and

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\_\_\_\_\_  
WILLIAM E. MCKINZIE, III (L.S.)  
DATE: Jan 11, 2017

PATENT